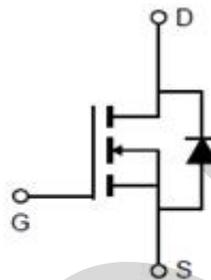


## SGT N-channel Power MOSFET

**TO-247**  
**MTR4R5N10PT**



$V_{DS}$	100	V
$R_{DS(on),TYP@ V_{GS}=10 V}$	3.2	m $\Omega$
$I_D$	200	A

### Features

- 1、 Low on – resistance
- 2、 Package TO-247
- 3、 SGT N-channel Power MOSFET

### Applications

- 1、 Load Switch for Portable Devices
- 2、 DC/DC Converter

**Maximum ratings, at  $T_A = 25^\circ\text{C}$ , unless otherwise specified**

Symbol	Parameter	Rating	Unit	
$V_{(BR)DSS}$	Drain-Source breakdown voltage	100	V	
$V_{GS}$	Gate-Source voltage	$\pm 20$	V	
$I_D$	Continuous drain current @ $V_{GS}=10V$	$T_C = 25^\circ\text{C}$ (Silicon limit)	220	A
		$T_C = 25^\circ\text{C}$ (Package limit)	200	A
		$T_C = 100^\circ\text{C}$ (Silicon limit)	110	A
$I_{DM}$	Pulse drain current tested ①	$T_C = 25^\circ\text{C}$	480	A
$E_{AS}$	Avalanche energy, single pulsed ②		900	mJ
$P_D$	Maximum power dissipation	$T_C = 25^\circ\text{C}$	227	W
$T_{STG}, T_J$	Storage and Junction Temperature Range		-55 to 150	$^\circ\text{C}$

## Thermal Characteristics

Symbol	Parameter	Typical	Unit
R <sub>θJC</sub>	Thermal Resistance, Junction-to-Case	0.44	°C/W
R <sub>θJA</sub>	Thermal Resistance, Junction-to-Ambient	60	°C/W

## Electrical Characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
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### Static Electrical Characteristics @ T<sub>j</sub>=25°C (unless otherwise stated)

V(BR)DSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	100	--	--	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =100V, V <sub>GS</sub> =0V	--	--	1	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	--	--	±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	2.0	3.0	4.0	V
R <sub>DS(on)</sub>	Drain-Source On-State Resistance ④	V <sub>GS</sub> =10V, I <sub>D</sub> =50A	--	3.2	4.5	mΩ

### Dynamic Electrical Characteristics @ T<sub>j</sub> = 25°C (unless otherwise stated)

C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =50V, V <sub>GS</sub> =0V, f=1MHz	--	7300	--	pF
C <sub>oss</sub>	Output Capacitance		--	2700	--	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		--	309	--	pF
R <sub>g</sub>	Gate Resistance	V <sub>GS</sub> =0V, f=1MHz, V <sub>DS</sub> =0V	--	1.6	--	Ω
Q <sub>g</sub> (10V)	Total Gate Charge	V <sub>DS</sub> =50V, I <sub>D</sub> =50A, V <sub>GS</sub> =10V	--	90	--	nC
Q <sub>gs</sub>	Gate-Source Charge		--	30	--	nC
Q <sub>gd</sub>	Gate-Drain Charge		--	19	--	nC

## Switching Characteristics

Td(on)	Turn-on Delay Time	V <sub>DS</sub> =50V, V <sub>GS</sub> =10V, R <sub>L</sub> =3.0Ω, T <sub>J</sub> =25°C	--	25	--	ns
Tr	Turn-on Rise Time		--	32	--	ns
Td(off)	Turn-Off Delay Time		--	48	--	ns
Tf	Turn-Off Fall Time		--	27	--	ns

## Source- Drain Diode Characteristics@ T<sub>J</sub> = 25°C (unless otherwise stated)

VSD	Forward on voltage	I <sub>SD</sub> =50A, V <sub>GS</sub> =0V	--	0.9	1.2	V
Trr	Reverse Recovery Time	I <sub>F</sub> =30A, di/dt=500A/μs	--	80	--	ns
Qrr	Reverse Recovery Charge	I <sub>F</sub> =30A, di/dt=500A/μs	--	185	--	nC

- NOTE: ① Repetitive rating; pulse width limited by max junction temperature.  
 ② Limited by T<sub>Jmax</sub>, starting T<sub>J</sub> = 25°C, L = 0.5mH, R<sub>G</sub> = 25Ω, I<sub>AS</sub> = 9A, V<sub>GS</sub> = 10V. Part not recommended for use above this value  
 ③ The power dissipation P<sub>DSM</sub> is based on R<sub>θJA</sub> and the maximum allowed junction temperature of 150°C.  
 ④ Pulse width ≤ 380μs; duty cycle ≤ 2%.

## Typical Characteristics

Fig 1: Output Characteristics

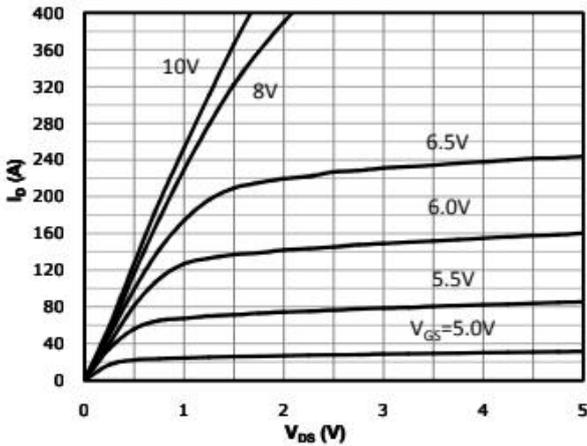


Fig 2: Transfer Characteristics

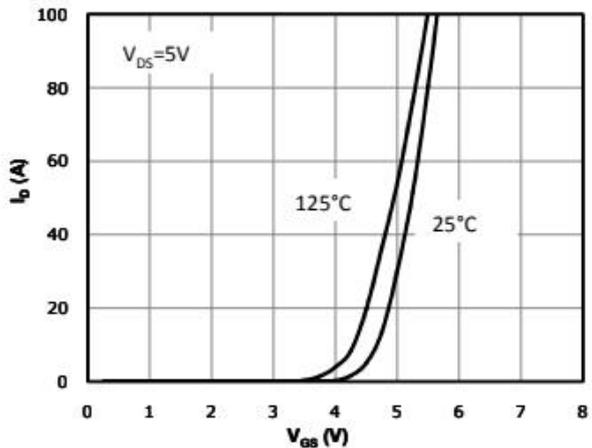


Fig 3: Rds(on) vs Drain Current and Gate Voltage

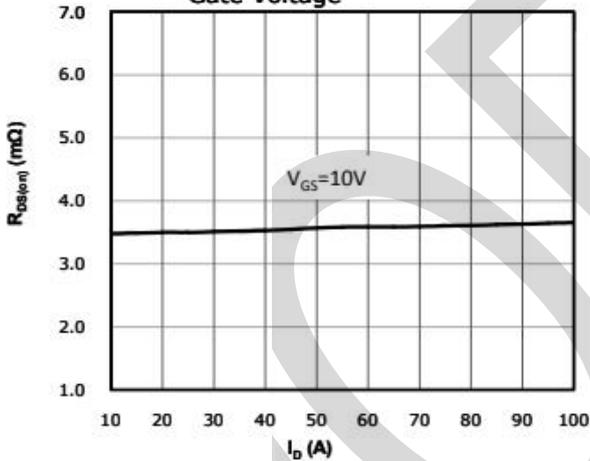


Fig 4: Rds(on) vs Gate Voltage

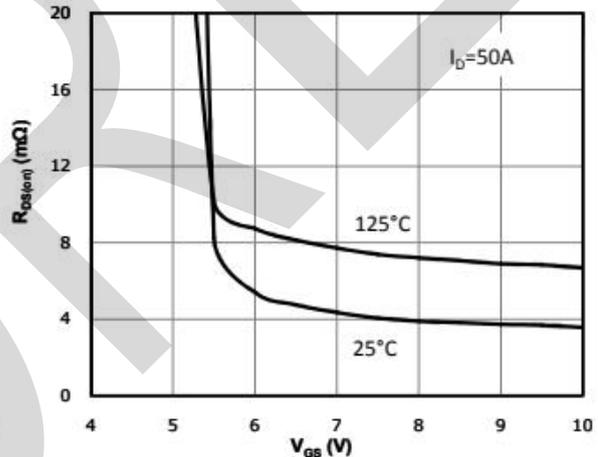


Fig 5: Rds(on) vs. Temperature

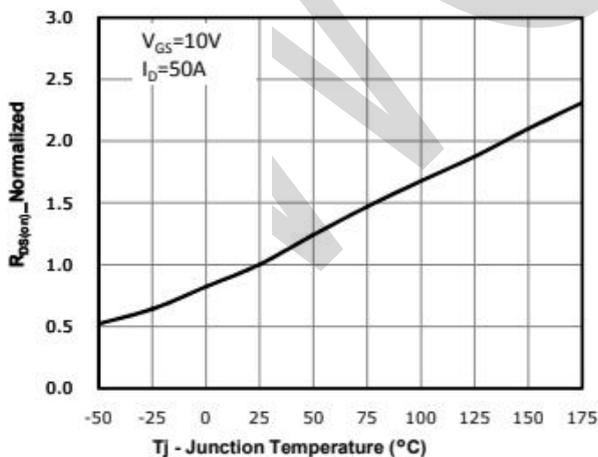
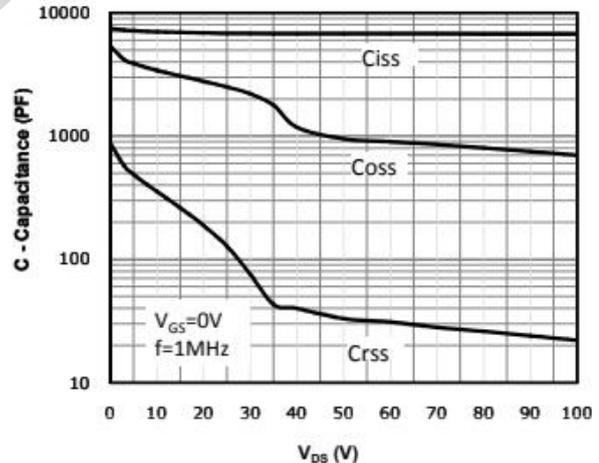


Fig 6: Capacitance Characteristics



## Typical Characteristics

Fig 7: Gate Charge Characteristics

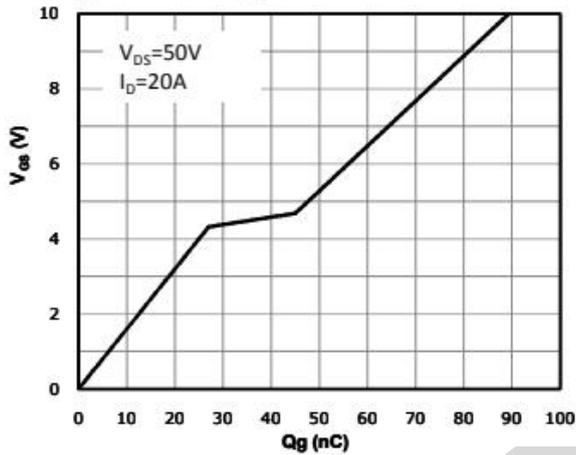


Fig 8: Body-diode Forward Characteristics

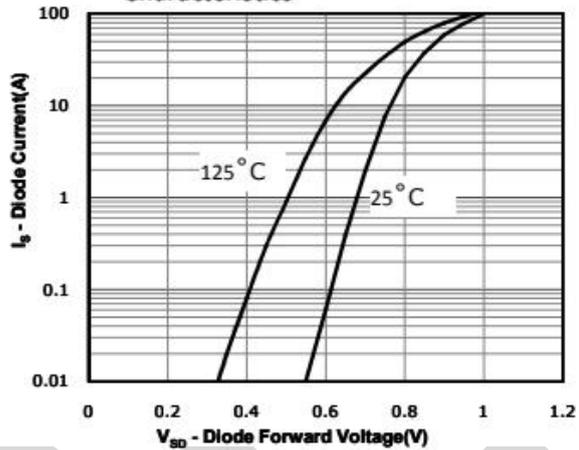


Fig 9: Power Dissipation

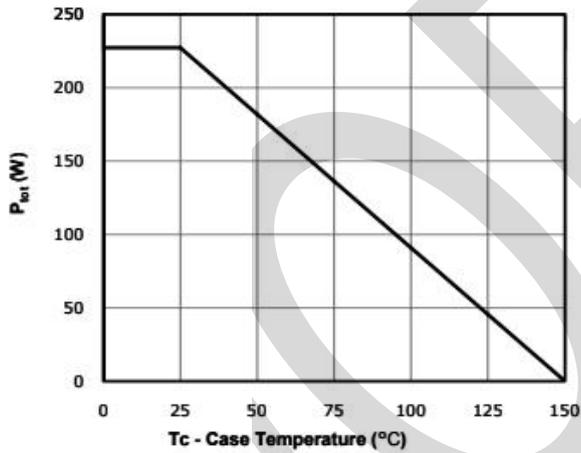


Fig 10: Drain Current Derating

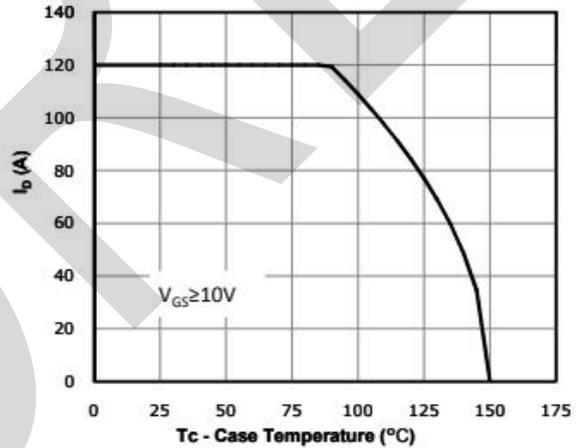
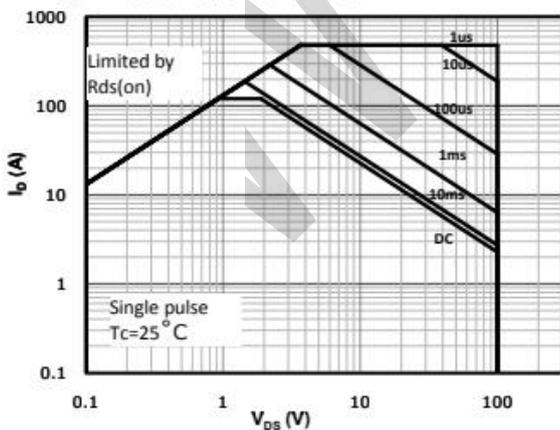
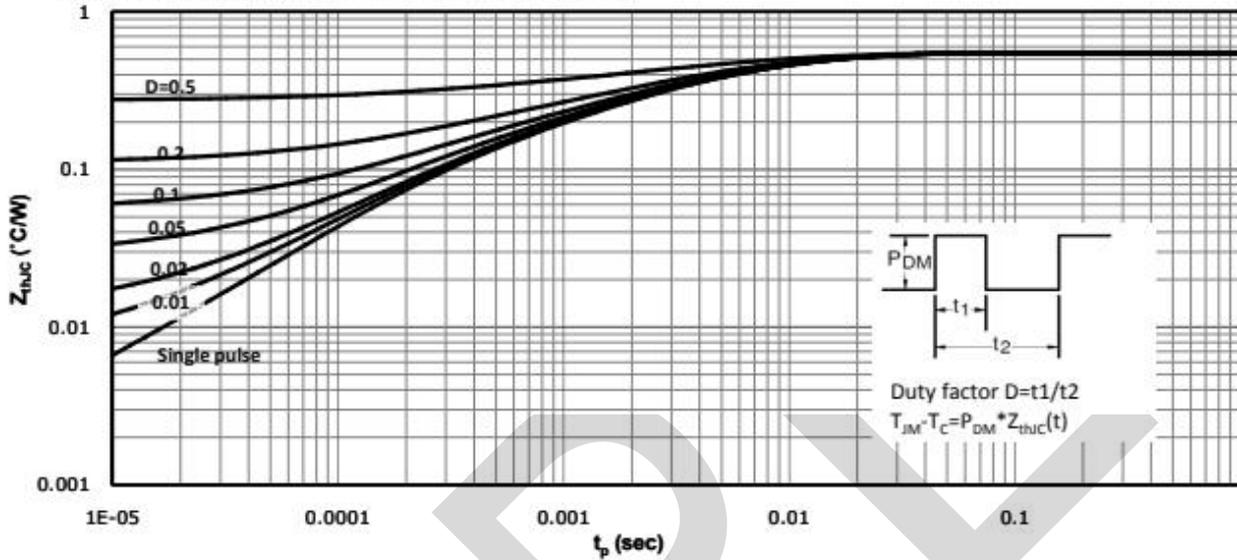


Fig 11: Safe Operating Area



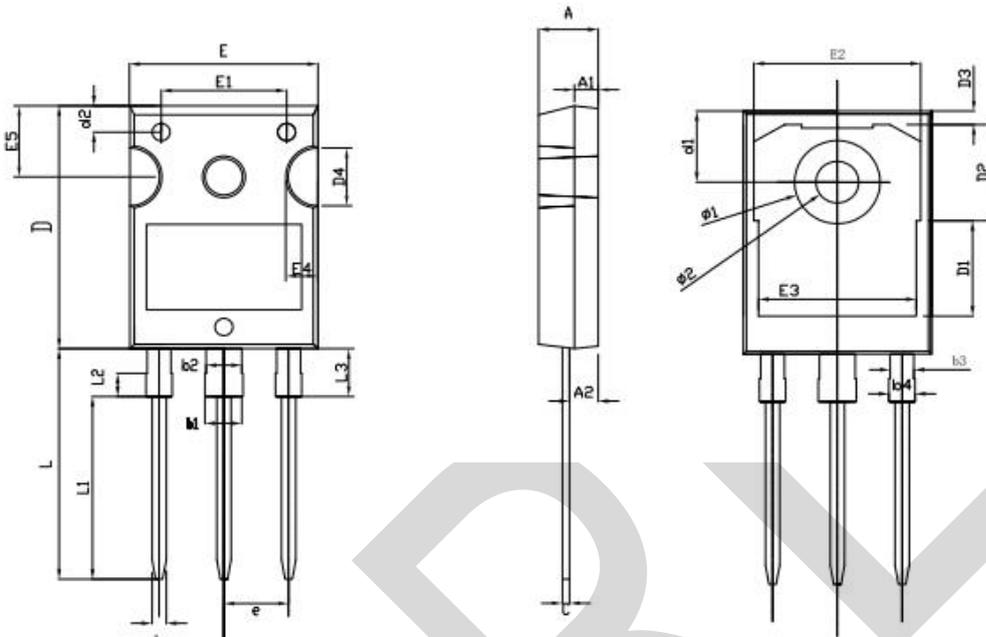
Typical Characteristics

Fig 12: Max. Transient Thermal Impedance

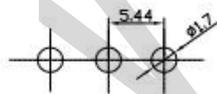


## PACKAGE OUTLINE DIMENSIONS

### TO-247



RECOMMENDED LAND PATTERN



UNIT: mm

	MIN	NOM	MAX
A	4.85	5.00	5.15
A1	1.90	2.00	2.10
A2	2.27	2.41	2.54
b	1.10	1.20	1.30
b1	2.90	-	3.20
b2	2.90	3.00	3.10
b3	1.90	2.00	2.10
b4	2.00	-	2.20
c	0.55	0.60	0.68
D	20.80	21.00	21.10
D1	-	8.23	-
D2	-	8.32	-
D3	-	1.17	-
D4	3.68	4.90	5.10
d1	6.04	6.15	6.30
d2	2.20	2.30	2.40
E	15.70	15.80	16.00
E1	-	10.50	-
E2	-	14.02	-
E3	-	13.50	-
E4	2.20	2.40	2.60
E5	5.49	5.80	6.00
e	5.34	5.44	5.54
L	19.72	19.92	20.12
L1	-	15.79	-
L2	-	1.98	-
L3	4.00	4.10	4.47
φ1	7.10	7.19	7.30
φ2	3.50	3.60	3.70